

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hidenori Aonuma</td> <td>08/17/2005</td> </tr> <tr> <td>Tetsuya Ohsawa</td> <td>08/17/2005</td> </tr> <tr> <td>Yasuhito Ohwaki</td> <td>08/17/2005</td> </tr> </tbody> </table>		Name	Execution Date	Hidenori Aonuma	08/17/2005	Tetsuya Ohsawa	08/17/2005	Yasuhito Ohwaki	08/17/2005
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Hidenori Aonuma	08/17/2005								
Tetsuya Ohsawa	08/17/2005								
Yasuhito Ohwaki	08/17/2005								
RECEIVING PARTY DATA									
Name:	Nitto Denko Corporation								
Street Address:	1-2, Shimohozumi 1-chome								
City:	Ibaraki-shi, Osaka								
State/Country:	JAPAN								
Postal Code:	567-8680								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11195965</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11195965				
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Application Number:	11195965								
CORRESPONDENCE DATA									
Fax Number:	(312)616-5700								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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NAME OF SUBMITTER:	John Kilyk, Jr.								
Total Attachments: 2 source=US 11_195,965 [LVM 238121] Assignment#page1.tif source=US 11_195,965 [LVM 238121] Assignment#page2.tif									

CH \$40.00 11195965

Leydig, Voit & Mayer, Ltd.
Attorneys at Law
Two Prudential Plaza
Suite 4900
180 North Stetson
Chicago, Illinois 60601-6780

ASSIGNMENT OF APPLICATION FOR PATENT

WHEREAS, WE,

Hidenori AONUMA of c/o Nitto Denko Corporation, 1-2, Shimohozumi 1-chome, Ibaraki-shi, Osaka
567-8680 Japan

(full name and address, including postal code, of first inventor)

Tetsuya OHSAWA of c/o Nitto Denko Corporation, 1-2, Shimohozumi 1-chome, Ibaraki-shi, Osaka
567-8680 Japan

(full name and address, including postal code, of second inventor)

Yasuhito OHWAKI of c/o Nitto Denko Corporation, 1-2, Shimohozumi 1-chome, Ibaraki-shi, Osaka
567-8680 Japan

(full name and address, including postal code, of second inventor)

respectively, have invented and own a certain new and useful invention entitled:

**PARTIALLY COMPLETED WIRING CIRCUIT BOARD ASSEMBLY SHEET AND PRODUCTION
METHOD OF WIRING CIRCUIT BOARD USING SAID SHEET**

for which invention we have executed an application for Letters Patent of the United States which was filed
on August 3, 2005, under Serial No. 11/195,965; and

WHEREAS,

Nitto Denko Corporation of 1-2, Shimohozumi 1-chome, Ibaraki-shi, Osaka 567-8680 Japan

(full name and address, including postal code, of assignee)

(hereinafter referred to as Assignee) is desirous of acquiring the entire right, title, and interest in and under the invention described in the application for Letters Patent.

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that for good and valuable considerations, the receipt and sufficiency of which are hereby acknowledged, we have assigned and set over, and by this document do assign and set over, to the Assignee and the Assignee's legal representatives, successors and assigns the entire right, title, and interest in and to the invention in the United States the applications for Letters Patent and other such applications (e.g., continuations, continuations-in-part, divisionals and reissues) in the United States, and the Letters Patent, or extensions thereof, that may or shall issue thereon; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue the Letters Patent to the above-mentioned Assignee agreeably with the terms of this Assignment.

WE HEREBY AUTHORIZE the above-mentioned Assignee to insert in this assignment document the filing date and serial number of the application if the date and number are unknown at the time this assignment is executed.

WE DO HEREBY COVENANT and agree with the Assignee that we will not execute any writing or do any act whatsoever conflicting with the terms of this assignment document set forth herein, and that we will at any time upon request, without further or additional consideration, but at the expense of the Assignee, execute such additional assignments and other writings and do such additional acts as the Assignee may deem necessary or desirable to perfect the Assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, divisional, continuation, renewal, reissued, or extended Letters Patent of the United States or of any and all foreign countries on the invention, and in enforcing any rights or choses in action accruing as a result of such applications or patents, and by executing preliminary statements and other affidavits, it being understood that the foregoing covenant and agreement shall bind, and inure to the benefit of, the assigns and legal representatives of both parties.

IN WITNESS WHEREOF, we have hereunder set our hands on the dates shown below:

Hidenori Aonuma
Signature of First Inventor Hidenori AONUMA

August 17, 2005
Date

Tetsuya Ohsawa
Signature of Second Inventor Tetsuya OHSAWA

August 17, 2005
Date

Yasuhito Ohwaki
Signature of Third Inventor Yasuhito OHWAKI

August 17, 2005
Date

Yutaka Aoki August 17, 2005
Witness Yutaka AOKI Date

Koichiro Tada August 17, 2005
Witness Koichiro TADA Date

Yutaka Aoki August 17, 2005
Witness Yutaka AOKI Date

Koichiro Tada August 17, 2005
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